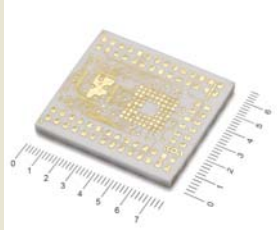


In automobiles, the incorporation of ceramic- and metal-based substrates as high heat-resistance substrates progresses. (page 16)



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